

SOT2084-2

HWFLGA18, thermal enhanced very-very thin fine-pitched land grid array package, 18 terminals, 0.4 mm pitch, 2.4 mm x 2 mm x 0.64 mm body

13 September 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HWFLGA18
Package style descriptive code	LGA (land grid array package)
Mounting method type	S (surface mount)
Issue date	17-08-2022
Manufacturer package code	98ASA01732D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.3	2.4	2.5	mm
package width	1.9	2	2.1	mm
seated height	-	0.64	0.7	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	18	-	



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2 Package outline

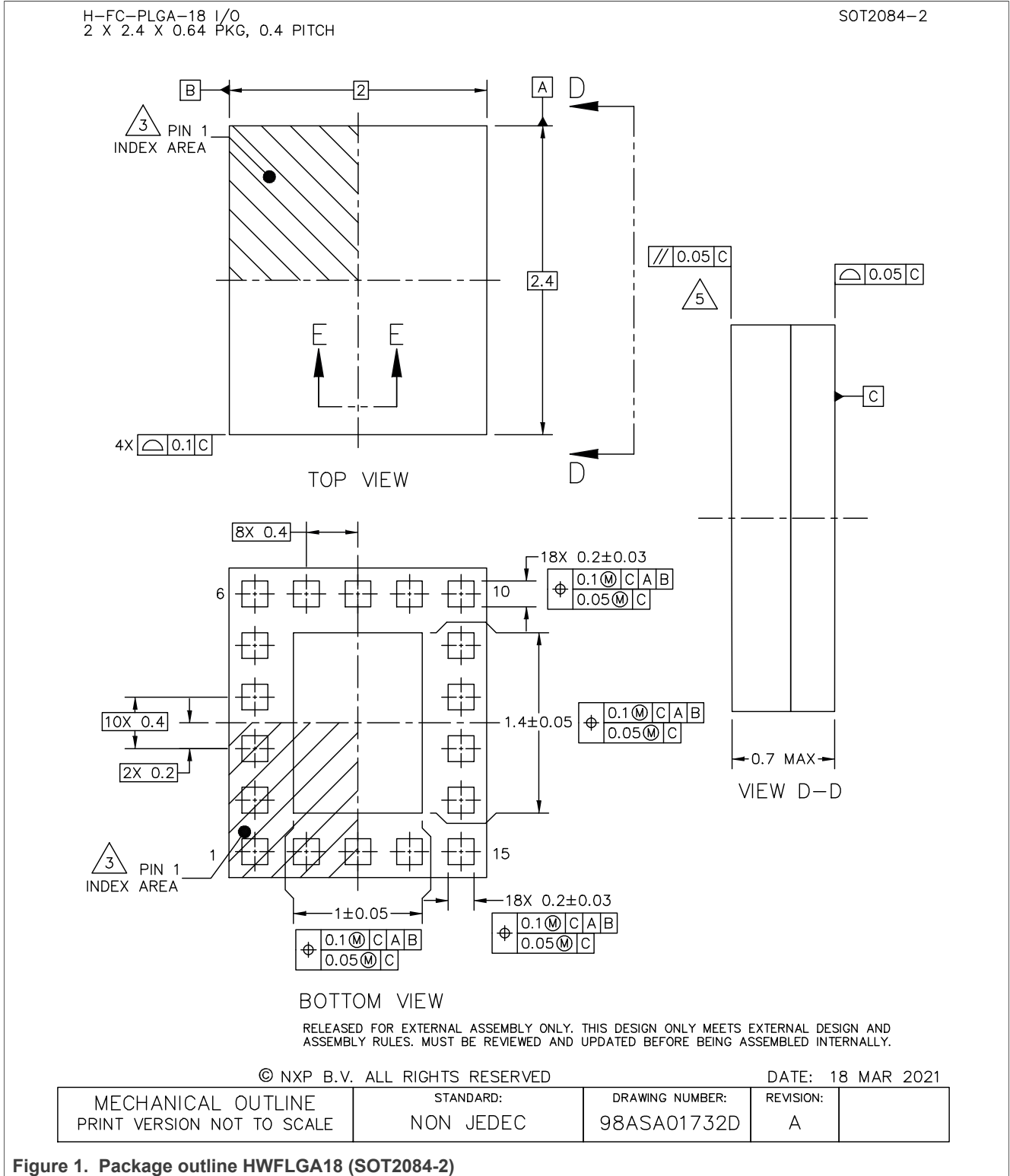


Figure 1. Package outline HWFLGA18 (SOT2084-2)

HWFLGA18, thermal enhanced very-very thin fine-pitched land grid array package, 18 terminals, 0.4 mm pitch, 2.4 mm x 2 mm x 0.64 mm body

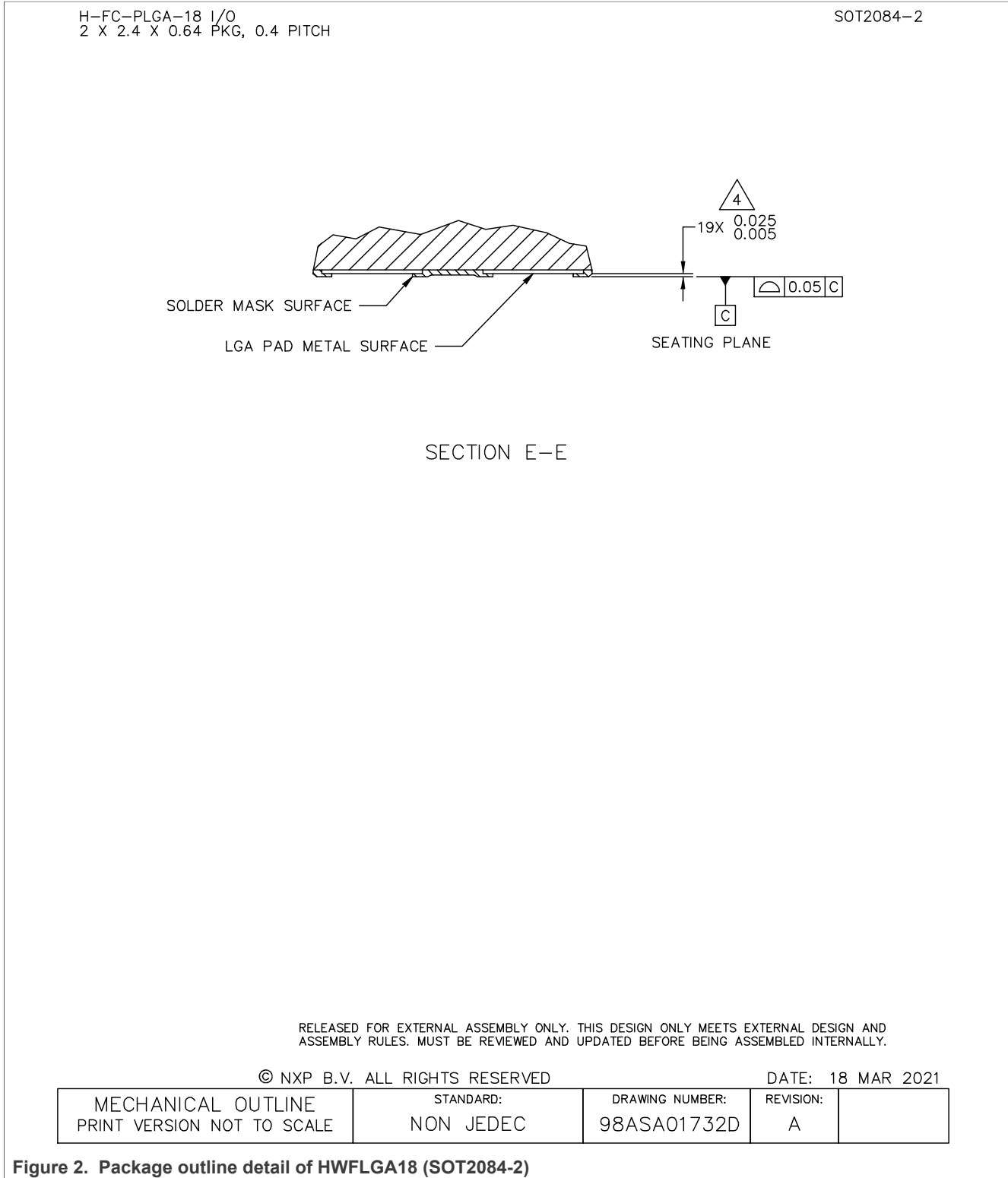
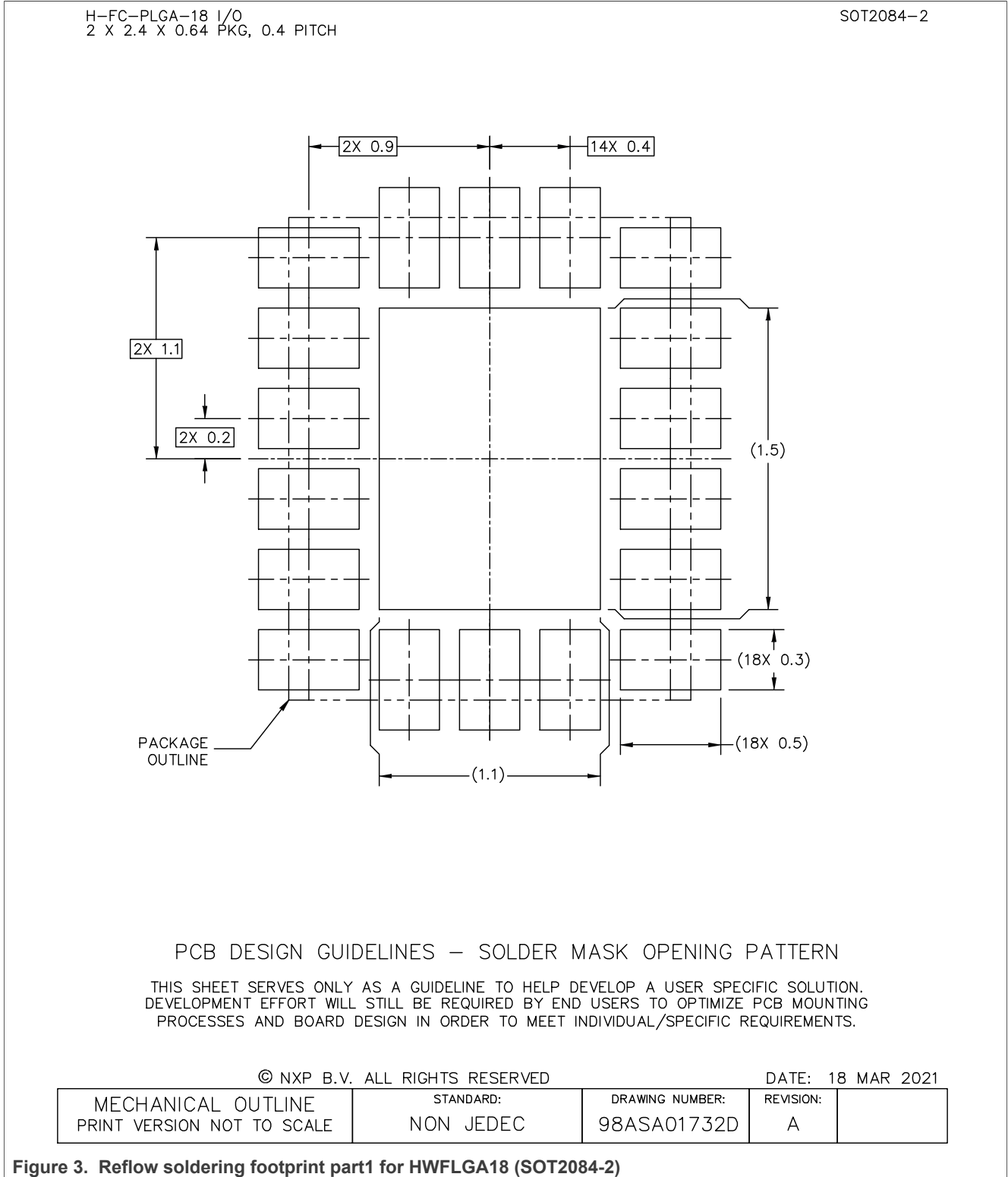


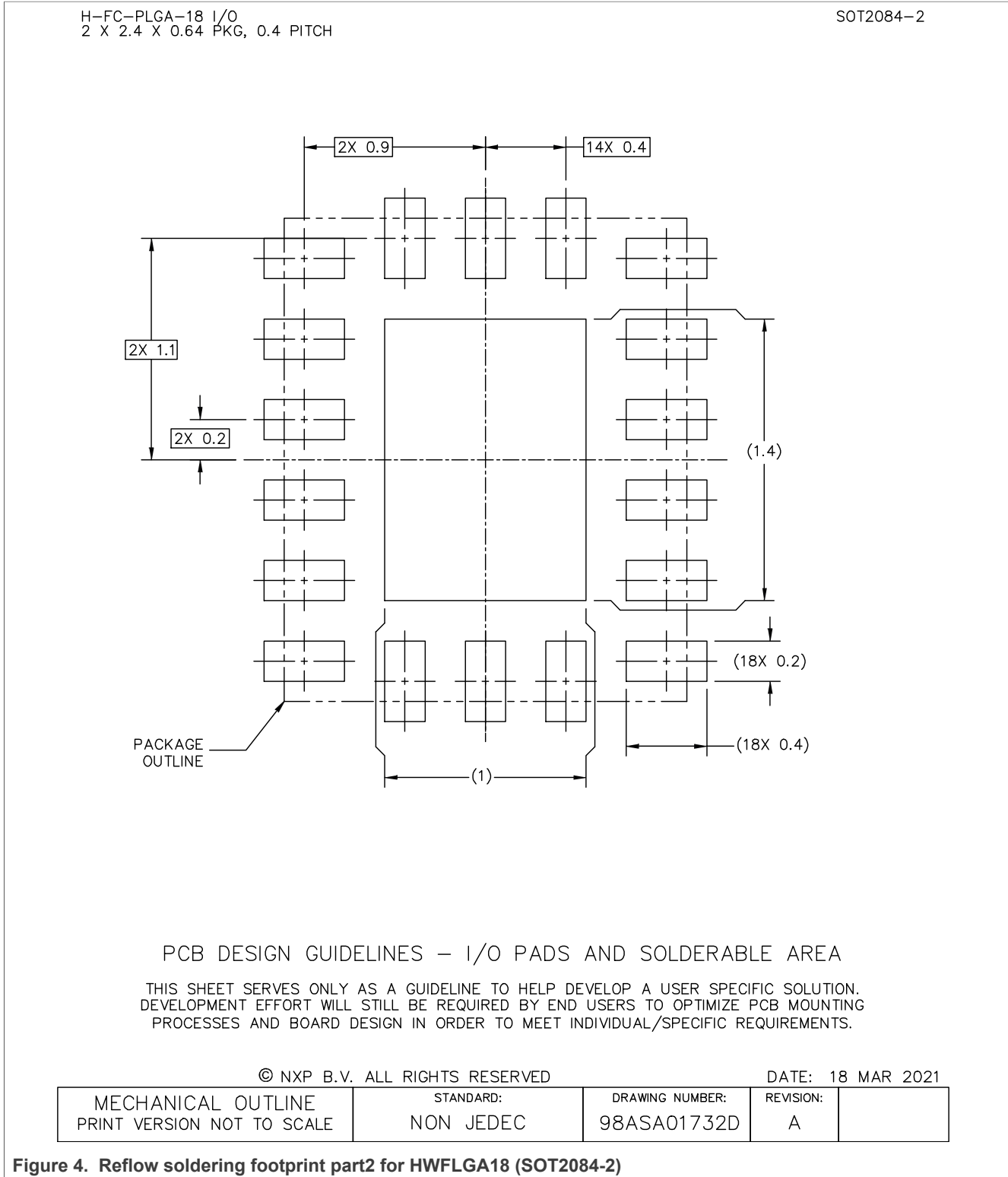
Figure 2. Package outline detail of HWFLGA18 (SOT2084-2)

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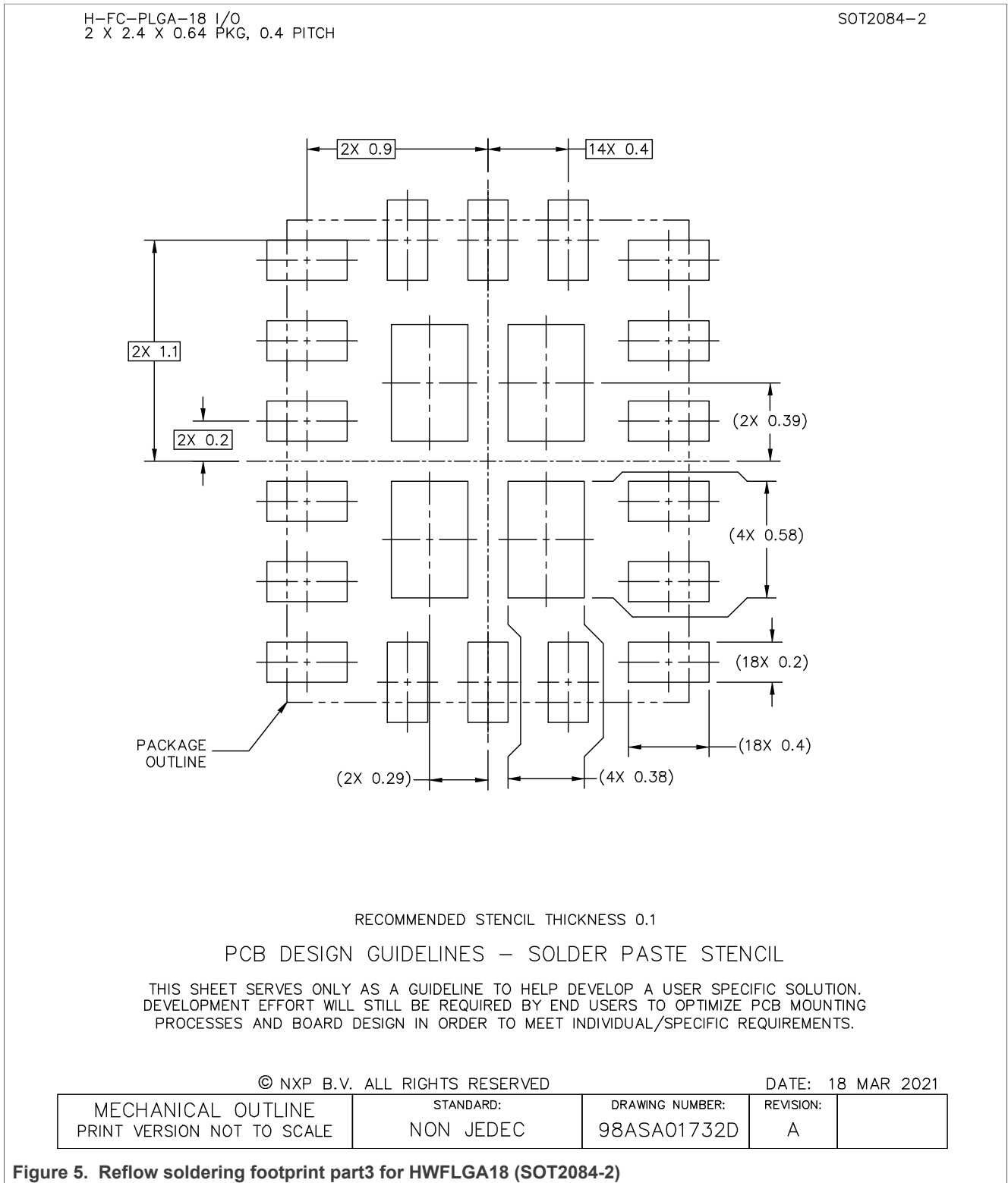
3 Soldering



HWFLGA18, thermal enhanced very-very thin fine-pitched land grid array package, 18 terminals, 0.4 mm pitch, 2.4 mm x 2 mm x 0.64 mm body



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H-FC-PLGA-18 I/O
2 X 2.4 X 0.64 PKG, 0.4 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE

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DATE: 18 MAR 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01732D	REVISION: A	
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Figure 6. Package outline note HWFLGA18 (SOT2084-2)

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4 Legal information

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